



PRINTED CIRCUIT BOARDS
INTERCONNECTION CARRIERS

State of the Art: PCB's

Revisio

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01

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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04 154 FR4 100 L41.105 P18

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_154_FR4_100_L41.105_p18

Layers	in μ	Material	Build-Up	Assembly
Layer-1	100 μ	Copper		} A1 } B
	180 μ	Prepreg		
	180 μ	Prepreg		
Layer-2	105 μ	Copper		
	410 μ	L-FR4		
Layer-3	105 μ	Copper		
	180 μ	Prepreg		
	180 μ	Prepreg		
Layer-99	100 μ	Copper		

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